

ABSTRACT

The present invention provides a method for connecting an integrated circuit to a substrate, which has the following steps: provision of a first electrical contact structure on a first main area of the integrated circuit; provision of a corresponding second electrical contact structure on an upper side of the substrate; at least one of the first and second electrical contact structures having elastic elevations; attachment of a second main area of the integrated circuit to a frame structure; placement of the first electrical contact structure onto the second electrical contact structure, so that the two are in electrical contact; and attachment of the frame structure to the substrate in such a way that the elastic elevations are under compressive stress. The invention likewise provides a corresponding circuit arrangement.

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